

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

LARRY ZHAO
JEREMY MARTIN
HARTMUT RUELKE

Serial No.: 10/717,122

Filed: November 19, 2003

For: DIELECTRIC BARRIER LAYER FOR A
COPPER METALLIZATION LAYER
HAVING A VARYING SILICON
CONCENTRATION ALONG ITS
THICKNESS

Confirmation No.: 7303

Examiner: Alexander G. Ghyka

Group Art Unit: 2812

Att'y Docket: 2000.106900/DE0130

Customer No.: 23720

ENTERED By RCE
FILED ON 1/14/08
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RESPONSE TO FINAL OFFICE ACTION DATED SEPTEMBER 13, 2007

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This paper is submitted in response to the Final Office Action dated September 13, 2007, for which the three-month date for response is December 13, 2007.

No fees are believed to be due in connection with the present paper. However, should any fees be required under 37 C.F.R. §§ 1.16 to 1.21, the Director is authorized to deduct such fees from Williams, Morgan & Amerson, P.C. Deposit Account No. 50-0786/2000.106900.

Reconsideration of the application in view of the following remarks is respectfully requested.